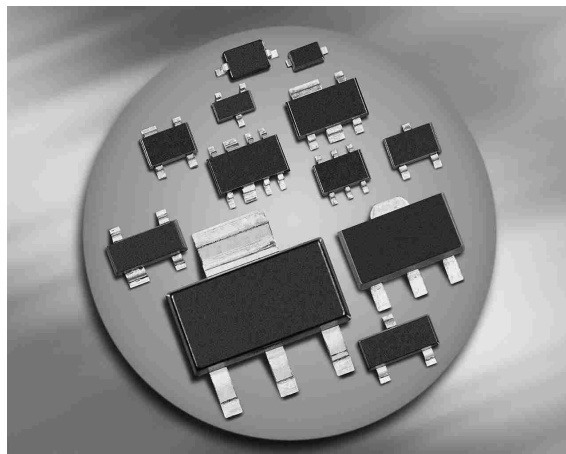


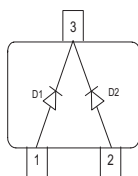
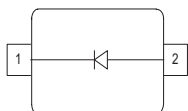
Silicon Tuning Diode

- High Q hyperabrupt tuning diode
- Designed for low tuning voltage operation for VCO's in mobile communications equipment
- High ratio at low reverse voltage
- Pb-free (RoHS compliant) package



BBY53-02L
BBY53-02V
BBY53-02W
BBY53-03W

BBY53
BBY53-05W



Type	Package	Configuration	L_S (nH)	Marking
BBY53	SOT23	common cathode	2	S7s
BBY53-02L	TSLP-2-1	single, leadless	0.4	LL
BBY53-02V	SC79	single	0.6	L
BBY53-02W	SCD80	single	0.6	LL
BBY53-03W	SOD323	single	1.8	white 5
BBY53-05W	SOT323	common cathode	1.4	S7s

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

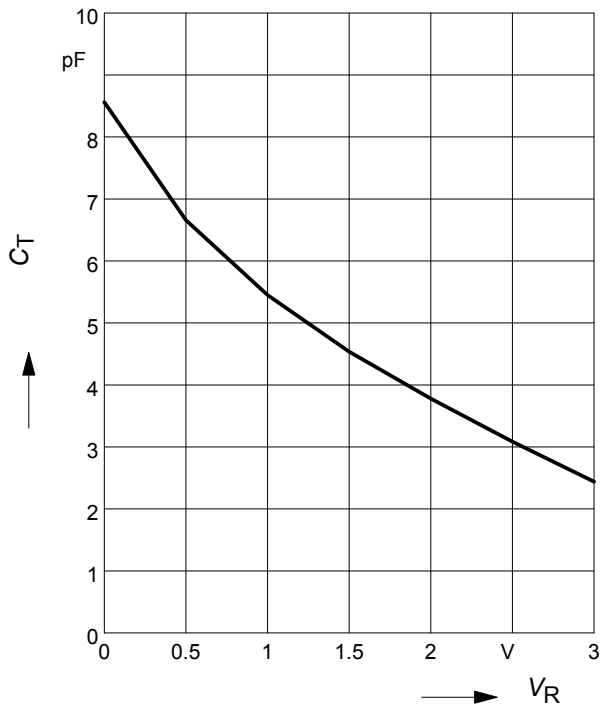
Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	6	V
Forward current	I_F	20	mA
Operating temperature range	T_{op}	-55 ... 125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 ... 150	

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current	I_R				nA
$V_R = 4\text{ V}$		-	-	10	
$V_R = 4\text{ V}, T_A = 85\text{ }^{\circ}\text{C}$		-	-	200	
AC Characteristics					
Diode capacitance	C_T				pF
$V_R = 1\text{ V}, f = 1\text{ MHz}$		4.8	5.3	5.8	
$V_R = 3\text{ V}, f = 1\text{ MHz}$		1.85	2.4	3.1	
Capacitance ratio	C_{T1}/C_{T3}	1.8	2.2	2.6	-
$V_R = 1\text{ V}, V_R = 3\text{ V}, f = 1\text{ MHz}$					
Series resistance	r_S	-	0.47	-	Ω
$V_R = 1\text{ V}, f = 1\text{ GHz}$					

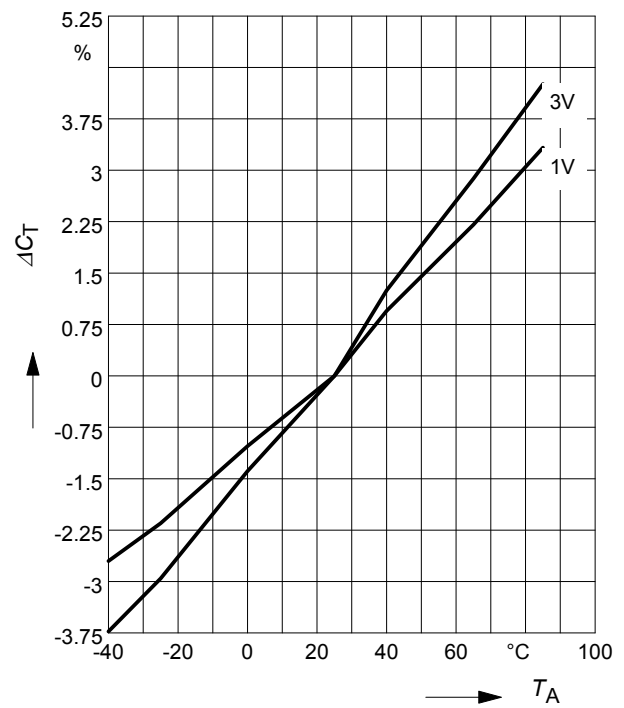
Diode capacitance $C_T = f(V_R)$

$f = 1\text{ MHz}$



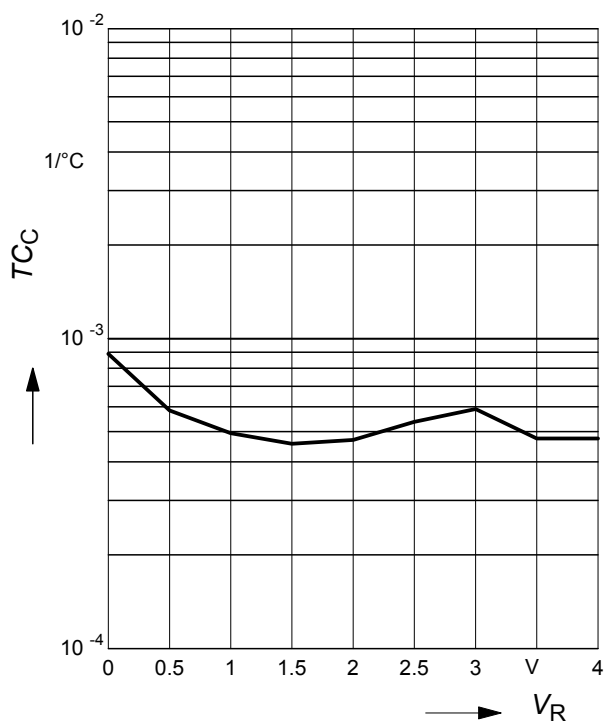
Capacitance change $\Delta C = f(T_A)$

$f = 1\text{ MHz}$



Temperature coefficient of the diode capacitance $TC_C = f(V_R)$

$f = 1\text{ MHz}$



[illegible]

Technical drawing of a stepped shaft. The drawing shows a shaft with a step. The distance between the centers of the two cylindrical sections is labeled as 1.35. The diameter of the smaller section is labeled as 0.35. The diameter of the larger section is also labeled as 0.35.

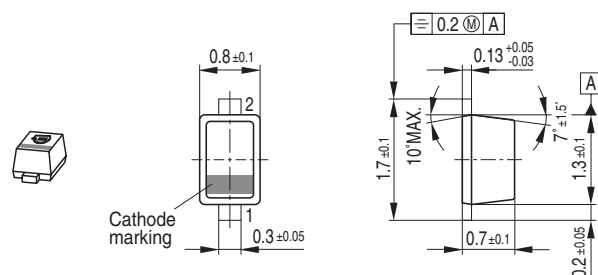
2005, June
Date code

GF

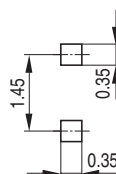
BAR63-02V
Type code

Cathode marking
Laser marking

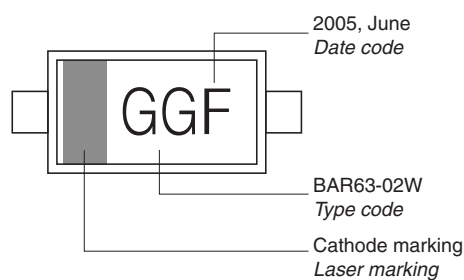
Package Outline



Foot Print

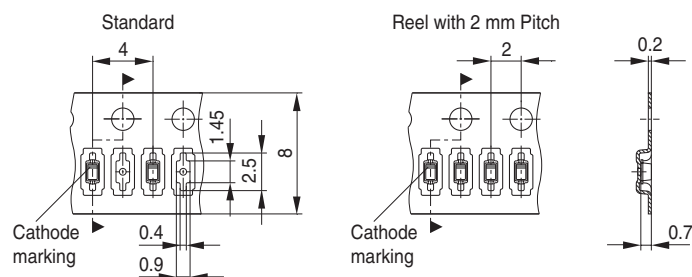


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel ø330 mm = 10.000 Pieces/Reel

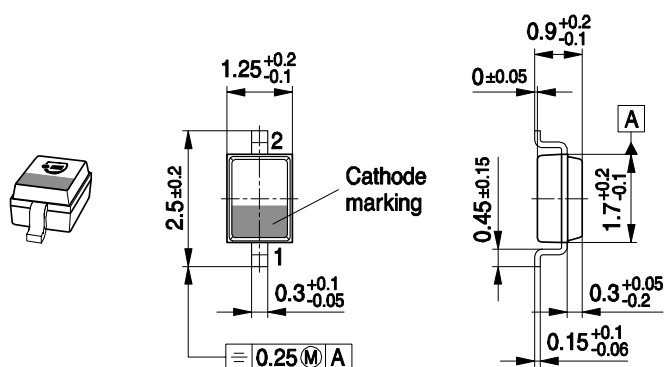


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

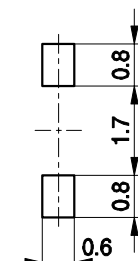
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

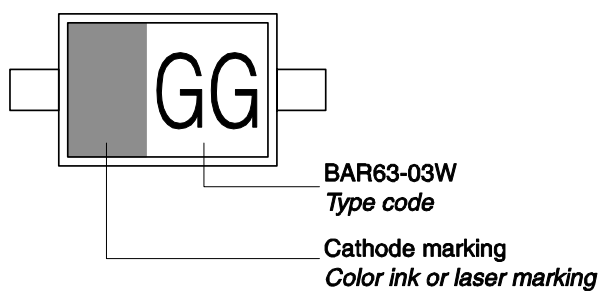
Package Outline



Foot Print

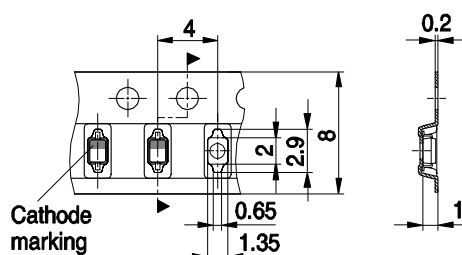


Marking Layout (Example)

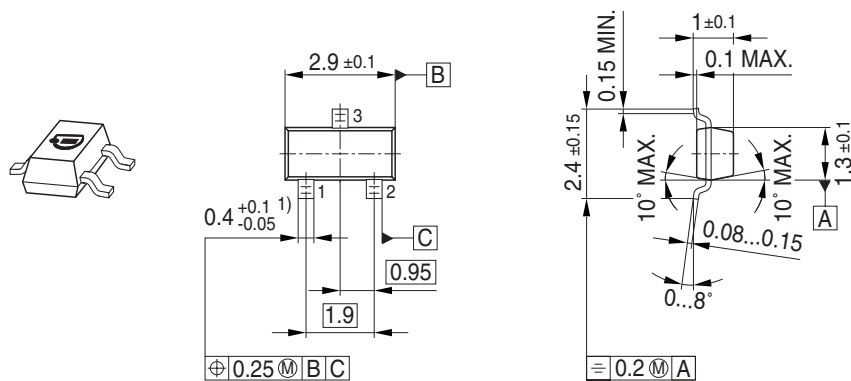


Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel

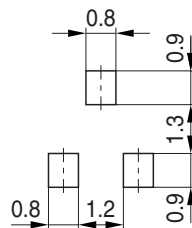


Package Outline

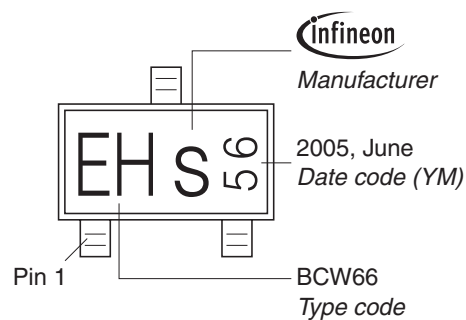


1) Lead width can be 0.6 max. in dambar area

Foot Print

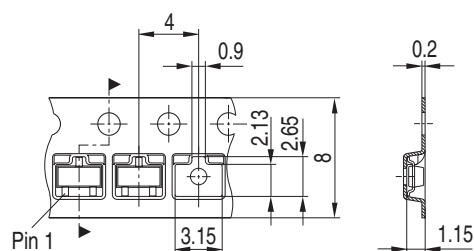


Marking Layout (Example)

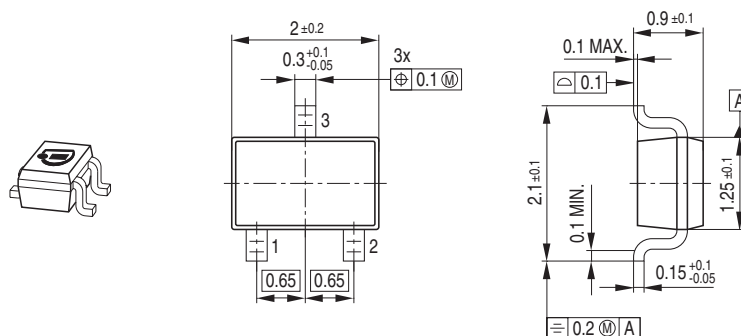


Standard Packing

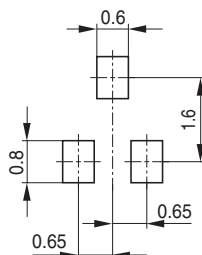
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



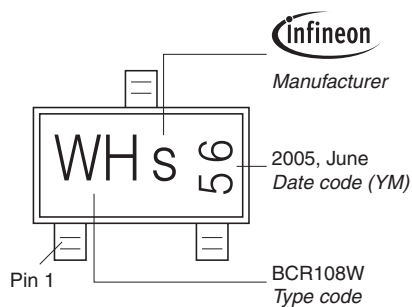
Package Outline



Foot Print

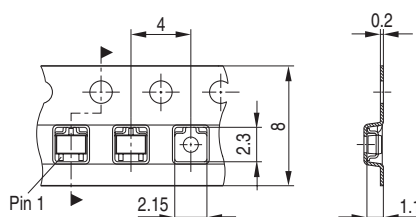


Marking Layout (Example)

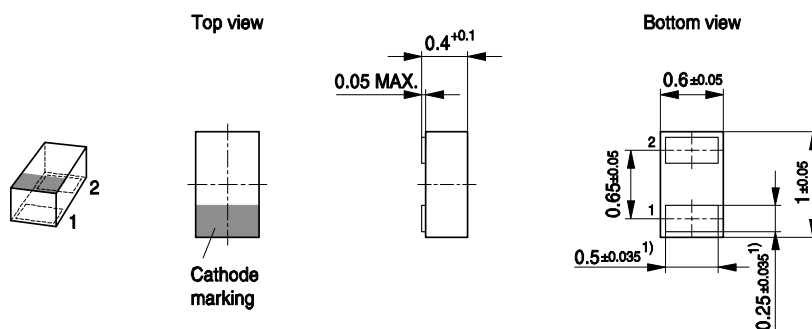


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

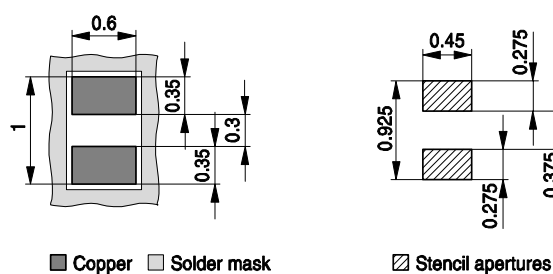


Package Outline

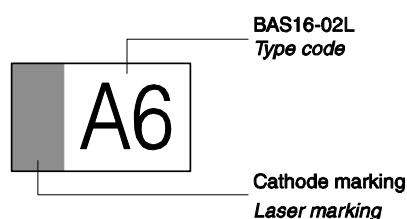


Foot Print

For board assembly information please refer to Infineon website "Packages"



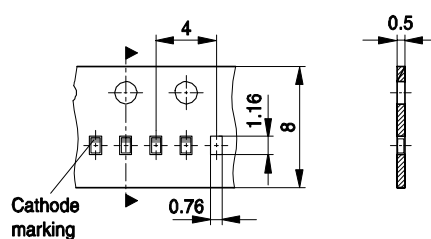
Marking Layout (Example)



Standard Packing

Reel $\varnothing$ 180 mm = 15.000 Pieces/Reel

Reel $\varnothing$ 330 mm = 50.000 Pieces/Reel (optional)



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